

n-Channel Power MOSFET

OptiMOS™
BSB014N04LX3 G

Data Sheet

2.3, 2011-05-24
Final

Industrial & Multimarket

1 Description

OptiMOS™40V products are class leading power MOSFETs for highest power density and energy efficient solutions. Ultra low gate- and output charges together with lowest on state resistance in small footprint packages make OptiMOS™ 40V the best choice for the demanding requirements of voltage regulator solutions in Servers, Datacom and Telecom applications. Super fast switching Control FETs together with low EMI Sync FETs provide solutions that are easy to design in. OptiMOS™ products are available in high performance packages to tackle your most challenging applications giving full flexibility in optimizing space- efficiency and cost. OptiMOS™ products are designed to meet and exceed the energy efficiency and power density requirements of the sharpened next generation voltage regulation standards in computing applications

Features

- Optimized for high switching frequency DC/DC converter
- 100% avalanche tested
- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free plating; RoHS compliant
- Very low on-resistance $R_{DS(on)}$
- Low profile (<0.7 mm)
- Low parasitic inductance
- Double.sided cooling
- Compatible with DirectFET® package MX footprint and outline
- 100% Rg Tested

Applications

- On board power for server
- Power managment for high performance computing
- Synchronous rectification
- High power density point of load converters

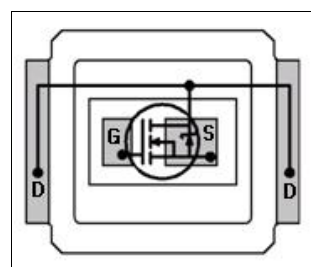


Table 1 Key Performance Parameters

Parameter	Value	Unit	Related Links
V_{DS}	40	V	IFX OptiMOS webpage IFX OptiMOS product brief IFX OptiMOS spice models IFX Design tools
$R_{DS(on),max}$	1.4	mΩ	
I_D	180	A	
Q_{OSS}	89	nC	
$Q_{g,typ}$	148		

Type	Package	Marking
BSB014N04LX3 G	MG-WDSO-2	0104

1) J-STD20 and JESD22

2 Maximum ratings

at $T_j = 25\text{ °C}$, unless otherwise specified.

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current	I_D	-	-	180	A	$V_{GS}=10\text{ V}$, $T_C=25\text{ °C}$
				128		$V_{GS}=10\text{ V}$, $T_C=100\text{ °C}$
				36		$V_{GS}=10\text{ V}$, $T_A=25\text{ °C}$, $R_{thJA}=45\text{ K/W}^{(1)}$
Pulsed drain current ⁽²⁾	$I_{D,pulse}$	-	-	400		$T_C=25\text{ °C}$
Avalanche current, single pulse ⁽³⁾	I_{AS}	-	-	50		
Avalanche energy, single pulse	E_{AS}	-	-	260	mJ	$I_D=50\text{ A}$, $R_{GS}=25\text{ }\Omega$
Gate source voltage	V_{GS}	-20	-	20	V	
Power dissipation	P_{tot}	-	-	89	W	$T_C=25\text{ °C}$
				2.8		$T_A=25\text{ °C}$, $R_{thJA}=45\text{ K/W}$
Operating and storage temperature	T_j, T_{stg}	-40	-	150	°C	
IEC climatic category; DIN IEC 68-1		55	150	56	Ncm	

1) J-STD22 and JESD22

2) See figure 3 for more detailed information

3) See figure 13 for more detailed information

3 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	1.0	-	°K/W	bottom
				1.4		top
Device on PCB	R_{thJA}	-	-	45		6 cm ² cooling area ⁽¹⁾

1) Device on 40 mm x 40 mm x 1.5 epoxy PCB FR4 with 6 cm² (one layer, 70µm thick) copper area for drain connection. PCB is vertical in still air.

4 Electrical characteristics

Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified.

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	40	-	-	V	$V_{GS}=0\text{ V}$, $I_D=1.0\text{ mA}$
Gate threshold voltage	$V_{GS(th)}$	1.2	-	2		$V_{DS}=V_{GS}$, $I_D=250\text{ }\mu\text{A}$
Zero gate voltage drain current	I_{DSS}	-	0.1	10	μA	$V_{DS}=40\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$
		-	10	100		$V_{DS}=40\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=125\text{ °C}$
Gate-source leakage current	I_{GSS}	-	10	100	nA	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	1.6	2	$\text{m}\Omega$	$V_{GS}=4.5\text{ V}$, $I_D=25\text{ A}$
		-	1.2	1.4		$V_{GS}=10\text{ V}$, $I_D=30\text{ A}$
Gate resistance	R_G	0.2	0.5	1.0	Ω	
Transconductance	g_{fs}	65	130		S	$ V_{DS} >2 I_{D} R_{DS(on)max}$, $I_D=30\text{ A}$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	12700	16900	pF	$V_{GS}=0\text{ V}$, $V_{DS}=20\text{ V}$, $f=1\text{ MHz}$
Output capacitance	C_{oss}	-	2400	3200		
Reverse transfer capacitance	C_{rss}	-	140	-		
Turn-on delay time	$t_{d(on)}$	-	12	-	ns	$V_{DD}=20\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=30\text{ A}$, $R_G=1.6\text{ }\Omega$
Rise time	t_r	-	8.4	-		
Turn-off delay time	$t_{d(off)}$	-	60	-		
Fall time	t_f	-	10	-		

Electrical characteristics
Table 6 Gate charge characteristics¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	33	-	nC	V_{DD} =20 V, I_D =30 A, V_{GS} =0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	19	-		
Gate to drain charge	Q_{gd}	-	15	-		
Switching charge	Q_{sw}	-	29	-		
Gate charge total	Q_g	-	148	196		
Gate plateau voltage	$V_{plateau}$	-	2.8	-	V	
Gate charge total	Q_g	-	71	95	nC	V_{DD} =20 V, I_D =30 A, V_{GS} =0 to 4.5V
Gate charge total, sync. FET	$Q_{g(sync)}$		139			V_{DS} =0.1 V, V_{GS} =0 to 10 V
Output charge	Q_{oss}		89			V_{DD} =20 V, V_{GS} =0 V

1) See figure 16 for gate charge parameter definition

Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_s			81	A	$T_C=25\text{ °C}$
Diode pulse current	$I_{s,pulse}$			400		
Diode forward voltage	V_{SD}	-	0.77	1.1	V	$V_{GS}=0\text{ V}$, $I_F=30\text{ A}$, $T_j=25\text{ °C}$
Reverse recovery charge	Q_{rr}	-	-	50	nC	$V_R=15\text{ V}$, $I_F=I_s$, $di_F/dt=400\text{ A}/\mu\text{s}$

5 Electrical characteristics diagrams

Table 8

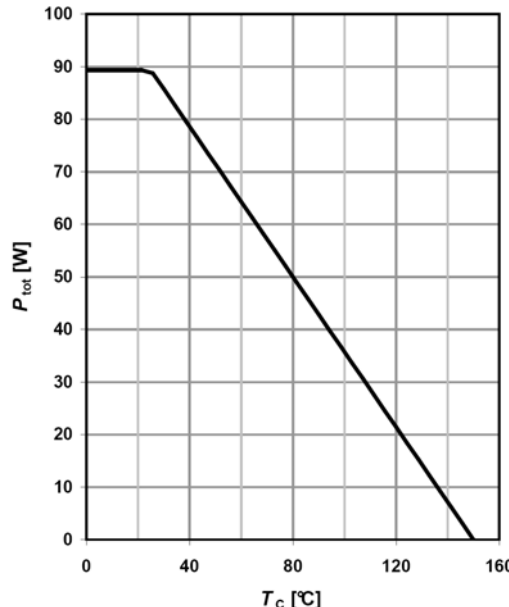
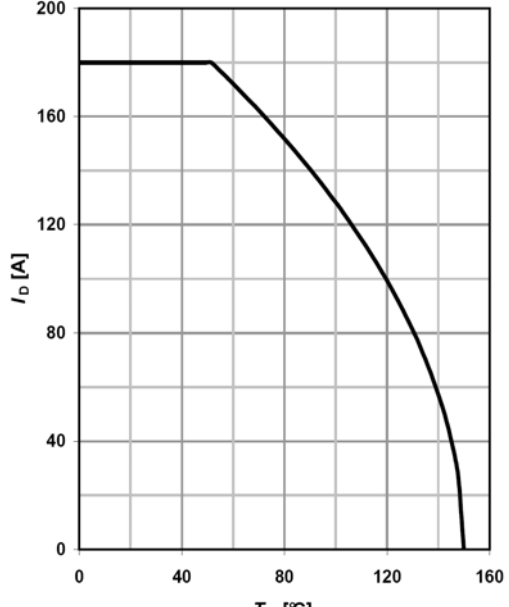
1 Power dissipation	2 Drain current
 $P_{\text{tot}} = f(T_c)$	 $I_D = f(T_c)$; parameter: V_{GS}

Table 9

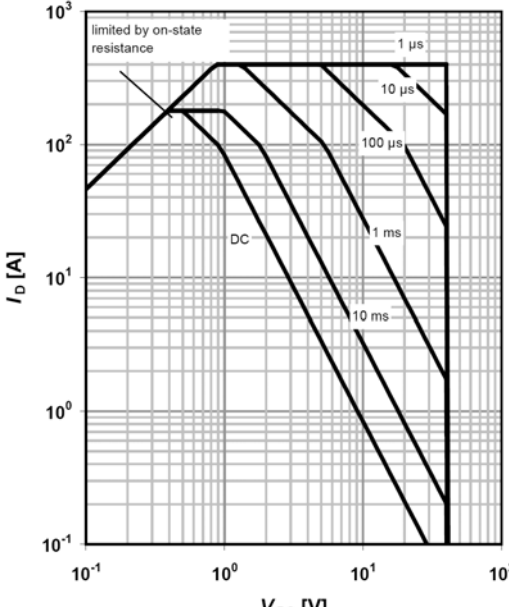
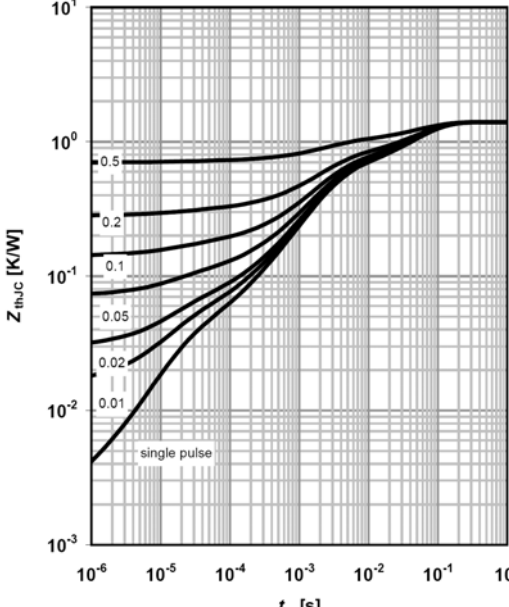
3 Safe operating area $T_c = 25\text{ °C}$	4 Max. transient thermal impedance
 $I_D = f(V_{DS})$; $T_J = 25\text{ °C}$; $D = 0$; parameter: T_p	 $Z_{(th)JC} = f(t_p)$; parameter: $D = t_p / T$

Table 10

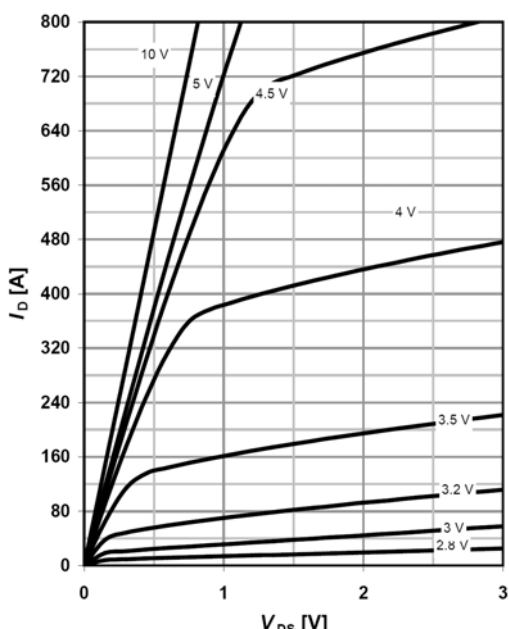
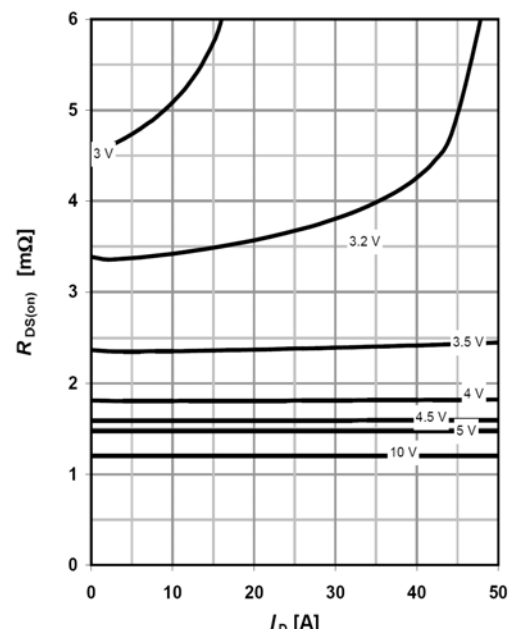
5 Typ. output characteristics $T_c=25\text{ °C}$	6 Typ. drain-source on-state resistance
 $I_D = f(V_{DS}); T_J = 25\text{ °C}; \text{parameter: } V_{GS}$	 $R_{DS(on)} = f(I_D); T_J = 25\text{ °C}; \text{parameter: } V_{GS}$

Table 11

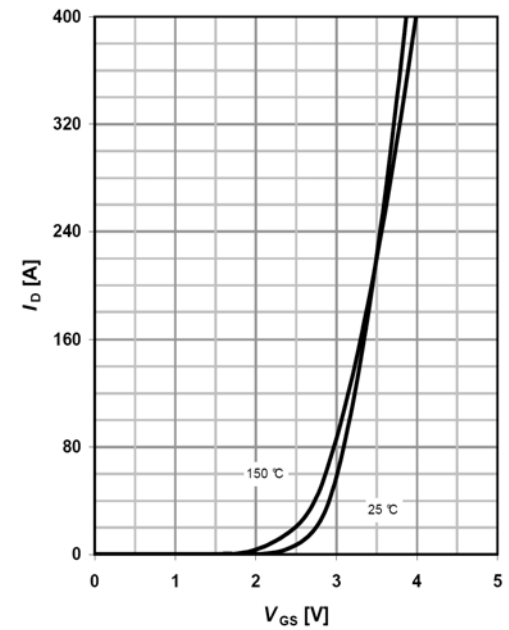
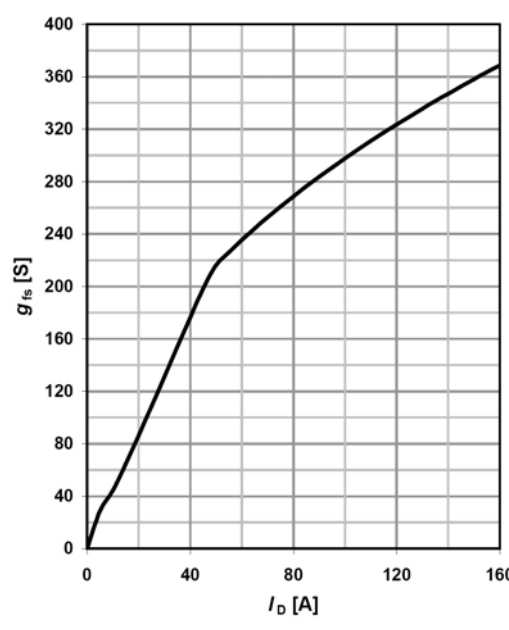
7 Typ. transfer characteristics	8 Typ. forward transconductance
 $I_D = f(V_{GS}); V_{DS} > 2 I_D R_{DS(on)max}$	 $g_{fs} = f(I_D); T_J = 25\text{ °C}$

Table 12

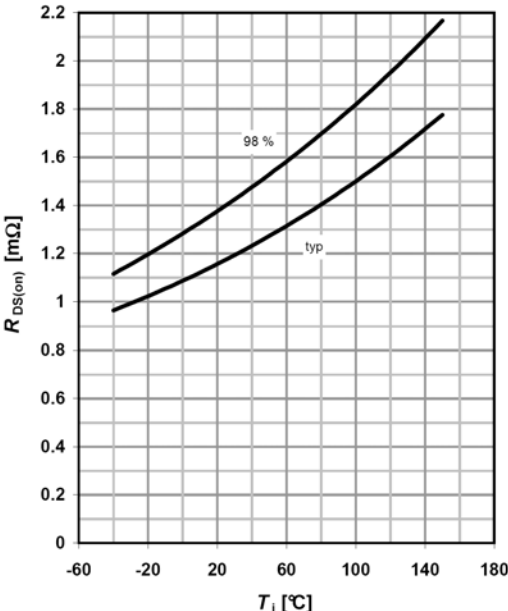
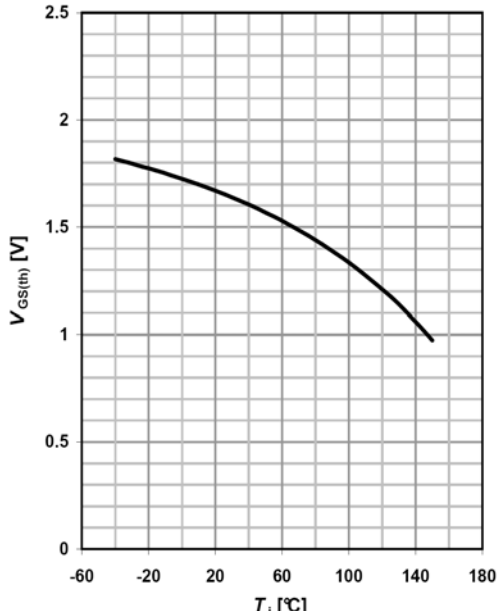
9 Drain-source on-state resistance	10 Typ. gate threshold voltage
	
$R_{DS(on)} = f(T_J); I_D = 30 \text{ A}; V_{GS} = 10 \text{ V}$	$V_{GS(th)} = f(T_J); V_{GS} = V_{DS}; I_D = 250 \mu\text{A}$

Table 13

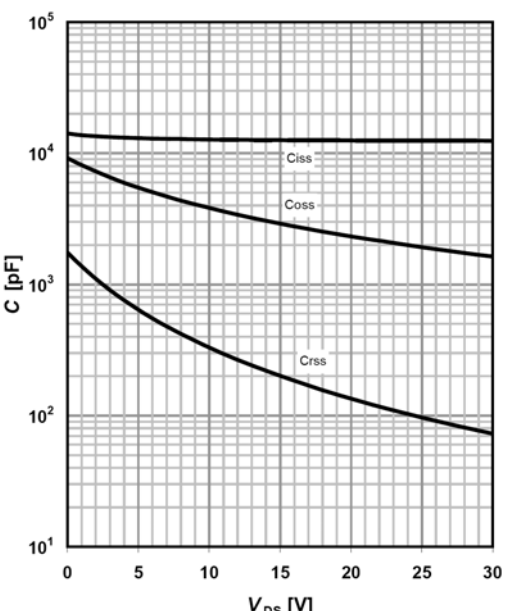
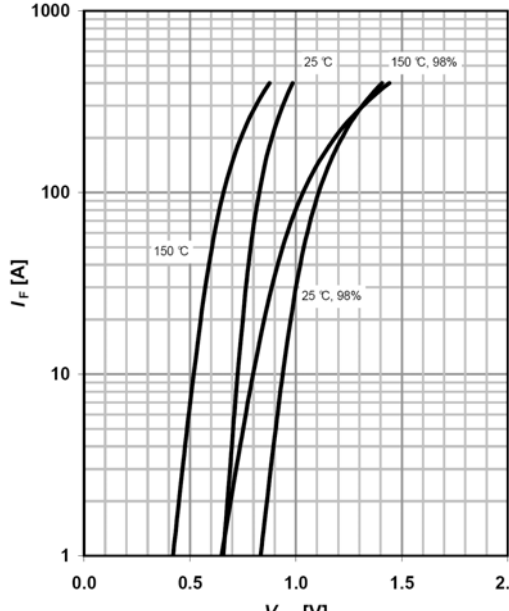
11 Typ. capacitances	12 Forward characteristics of reverse diode
	
$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$	$I_F = f(V_{SD}); \text{parameter: } T_J$

Table 14

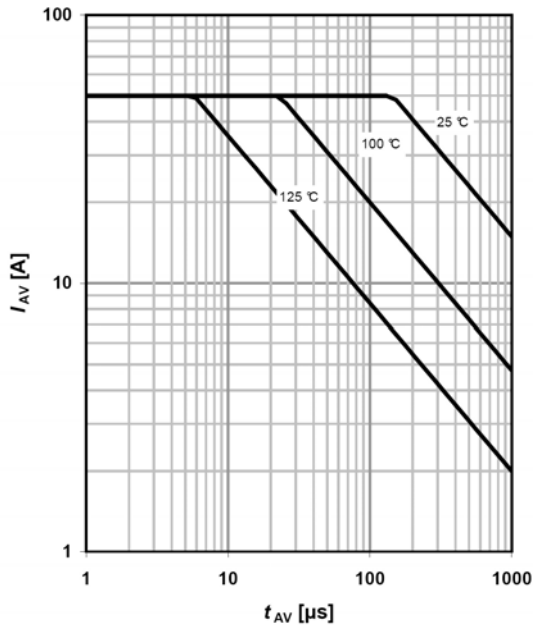
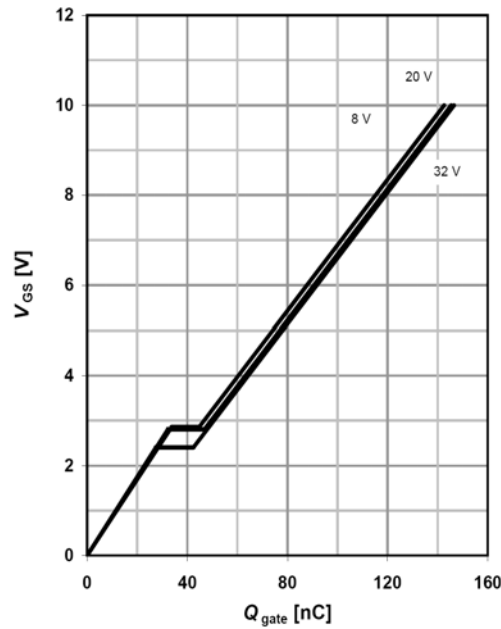
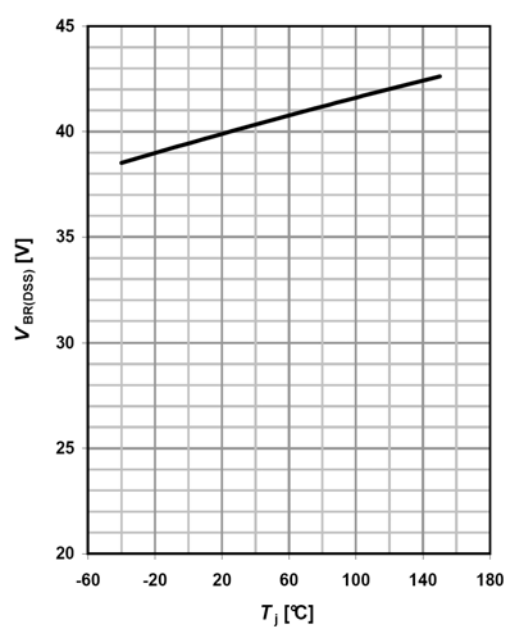
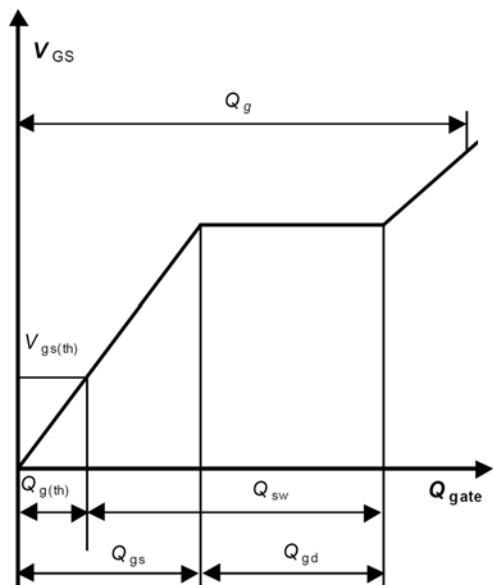
13 Avalanche characteristics	14 Typ. gate charge
 $I_{AS}=f(t_{AV}); R_{GS}=25\ \Omega$; parameter: $T_{j(start)}$	 $V_{GS}=f(Q_{gate}); I_D=30\text{ A pulsed}$; parameter: V_{DD}

Table 15

15 Drain-source breakdown voltage	16 Gate charge waveforms
 $V_{BR(DSS)}=f(T_j); I_D=1\text{ mA}$	

6 Package outlines

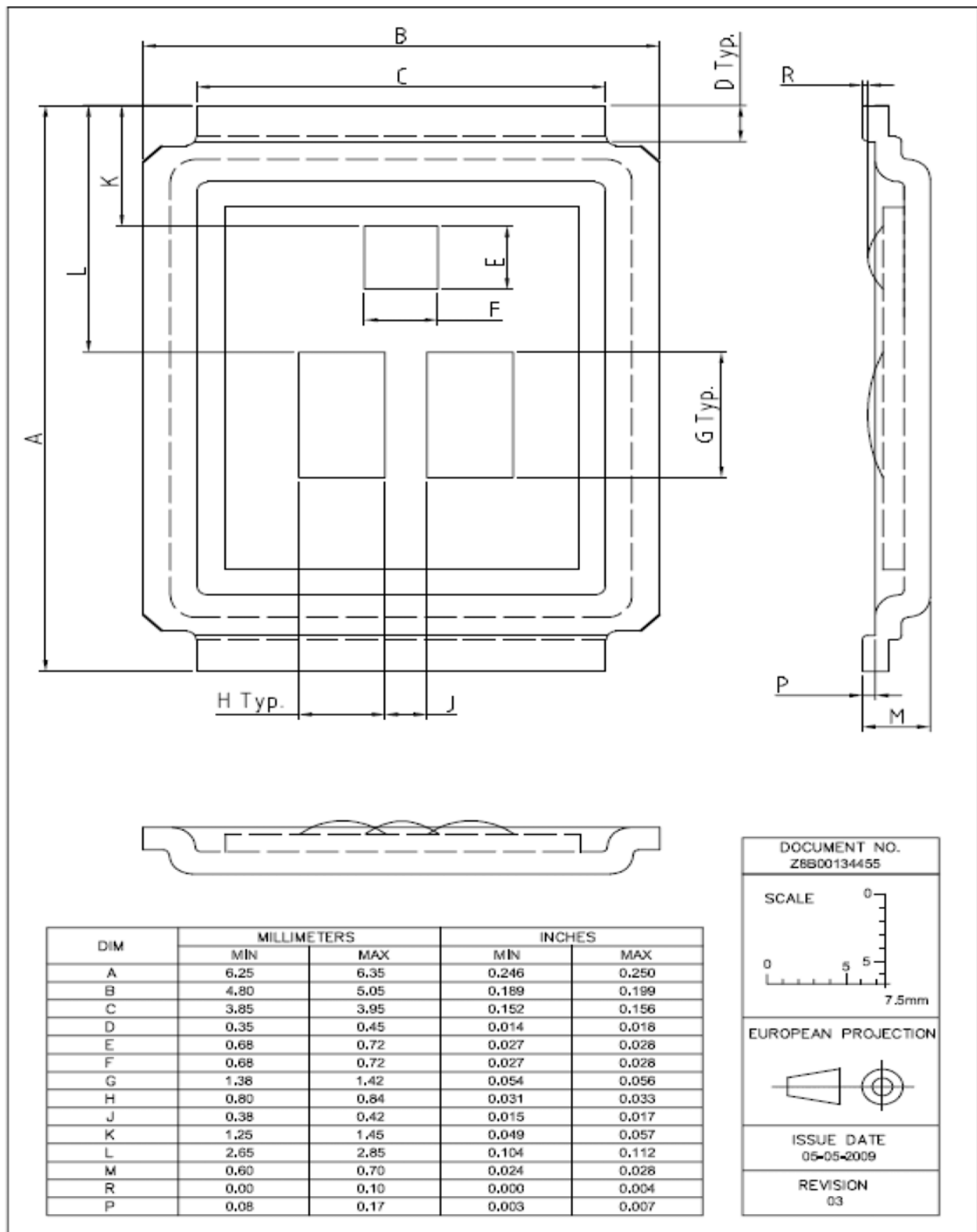


Figure 1 Outlines MG-WDSN-2, dimensions in mm/inches

7 Package outlines

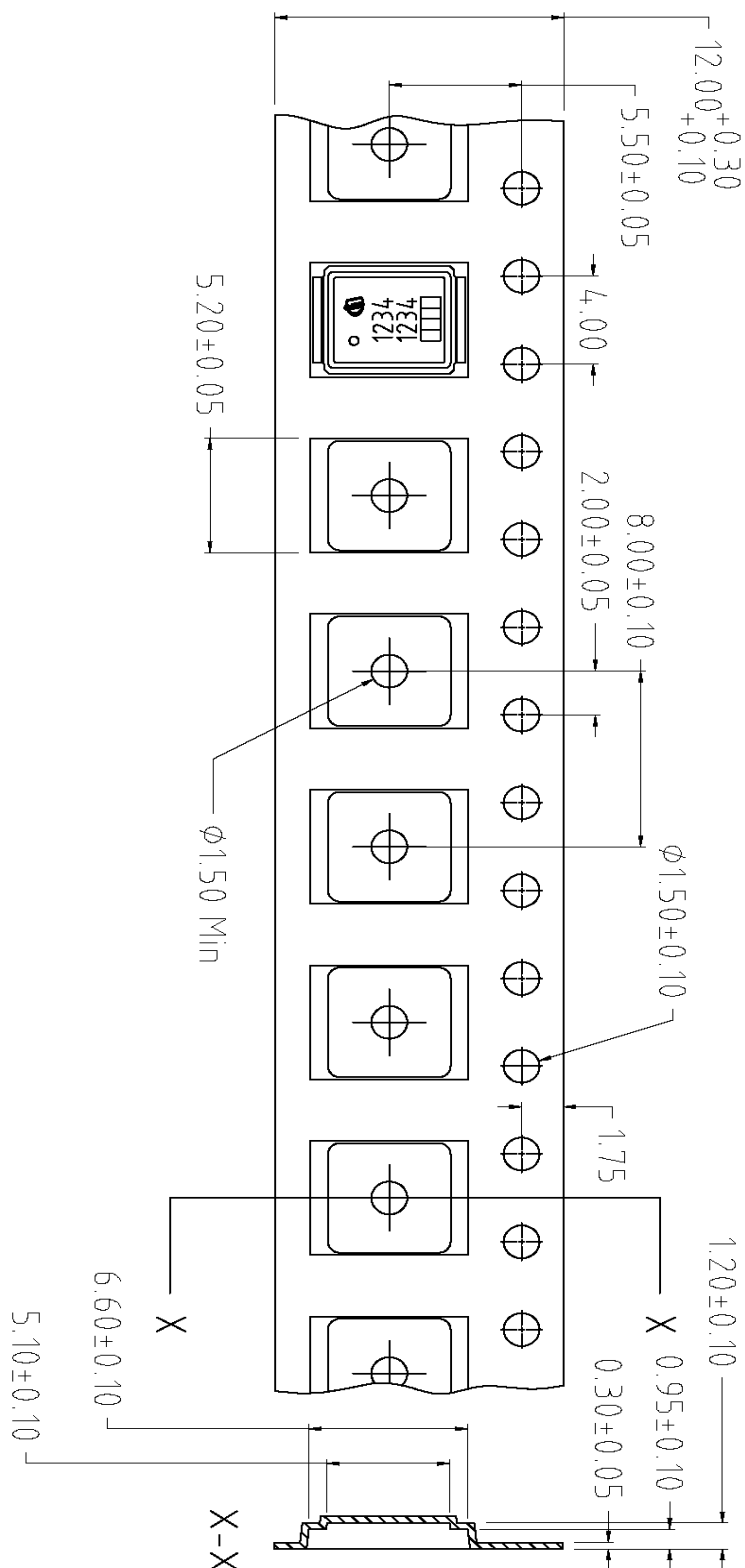


Figure 2 Outlines MG-WDSO-2, dimensions in mm/inches

8 Package outlines

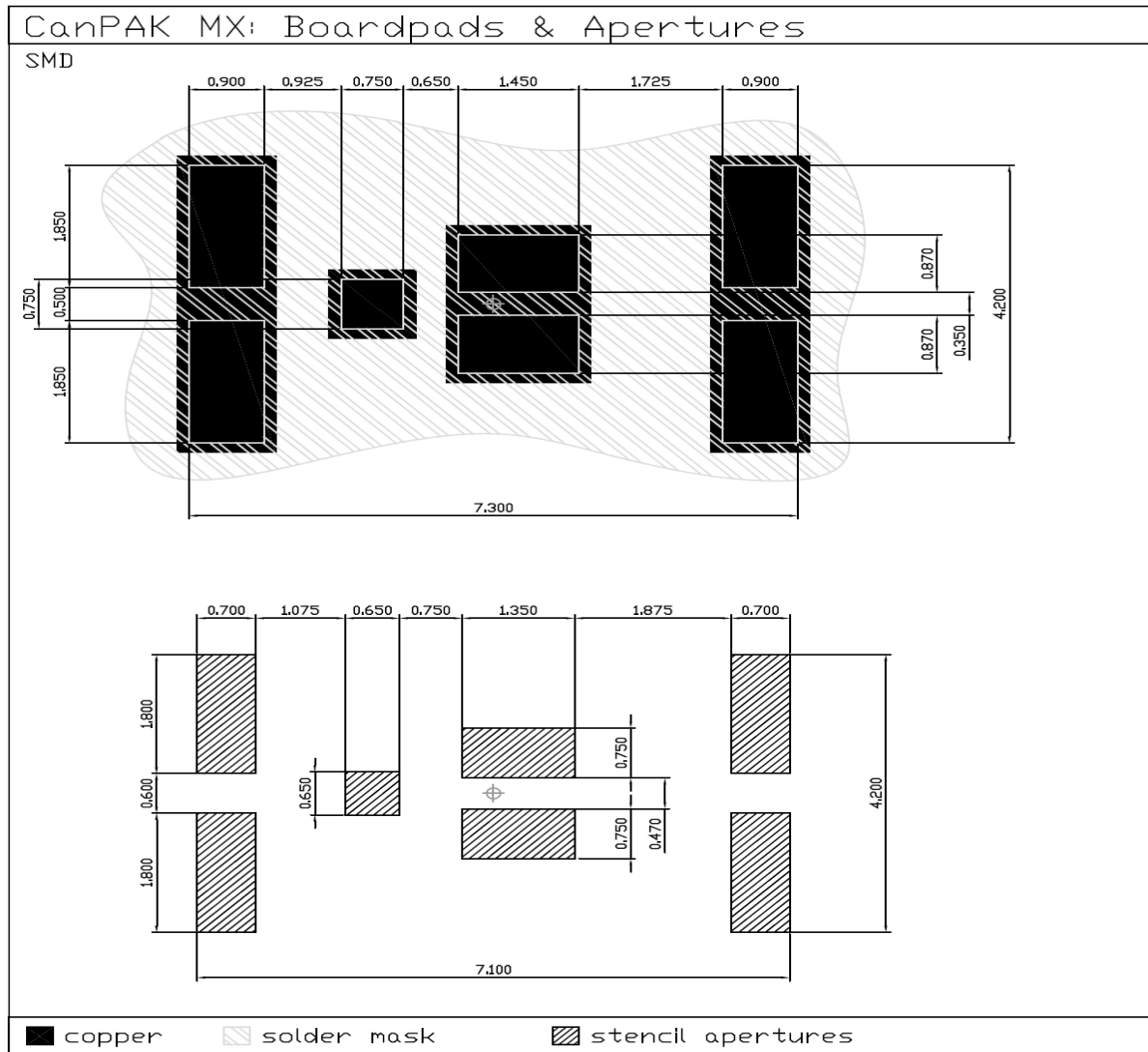
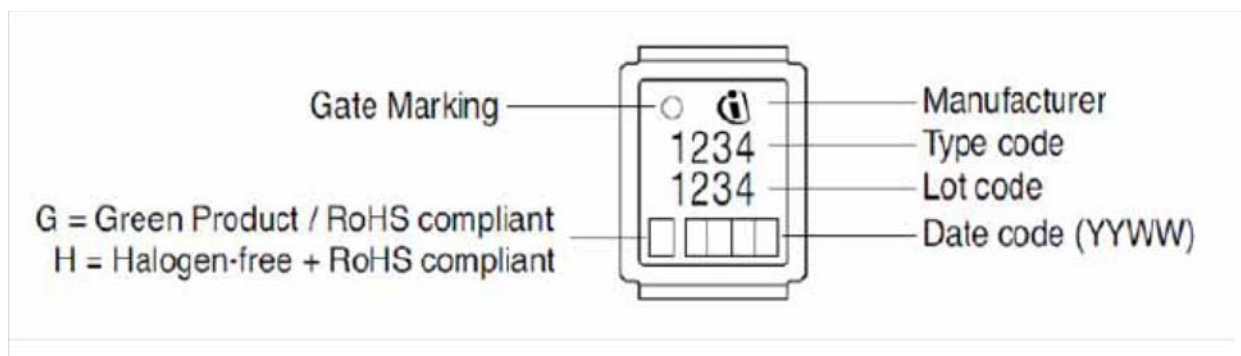


Figure 3 Outlines MG-WDSN-2, dimensions in mm/inches

9 Marking layout



9 Revision History

Revision History: 2011-05-24, 2.3

Previous Revision:

Revision	Subjects (major changes since last revision)
0.1	Release of target data sheet
2.2	DirectFET Disclaimer Expired
2.3	Insert Marking Layout

We Listen to Your Comments

Any information within this document that you feel is wrong, unclear or missing at all?

Your feedback will help us to continuously improve the quality of this document.

Please send your proposal (including a reference to this document) to: erratum@infineon.com



Edition 2011-05-24

Published by

Infineon Technologies AG

81726 Munich, Germany

© 2011 Infineon Technologies AG

All Rights Reserved.

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

The Infineon Technologies component described in this Data Sheet may be used in life-support devices or systems and/or automotive, aviation and aerospace applications or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support, automotive, aviation and aerospace device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.